

Amendments

Please amend the above-identified application as follows:

In the Drawings:

Kindly enter new Figures 8-10 enclosed herewith.

In the Specification:

Page 8, after line 16, kindly add the following paragraphs:

-- For example, as disclosed in the incorporated, commonly owned application 09/342,606, now U.S. Patent No. 6,285,506, such a device 500 is shown in FIGURE 8 and comprises a flexible layer 510, a thick epoxy layer 512 and a backing plate 514. The structure of the device is shown by the vertical cross-sectional view in FIGURE 9. In this device, the epoxy layer 512 holds and constrains the flexible layer 510 to a selected geometry having a curvature. Preferably, the thickness of the epoxy layer is greater than 20 μm and the thickness of the flexible layer is greater than 5 μm . Further, the thickness of the epoxy layer is typically thicker than the thickness of the flexible layer. The flexible layer can be one of a large variety of materials, including: mica, Si, Ge, quartz, plastic, glass etc. The epoxy layer 512 can be a paste type with viscosity in the order of 103 to 104 poise and 30 to 60 minutes pot life. The backing plate 514 can be a solid object that bonds well with the epoxy. The surface 518 of the backing plate can be flat (FIGURE 9) or curved as shown in FIGURE 10, and its exact shape and surface finish are not critical to the shape and surface finish of the flexible layer. This is contrasted with standard fabrication practices which require a backing plate with a surface that is exactly the desired shape of the device. Another drawback to the standard approach is that each device requires a specially prepared backing plate. In the invention disclosed here, a specially prepared backing plate is not required.